

## BRIEF DESCRIPTION OF THE DRAWINGS

[0005]       **Figures 1 A-K** are illustrations of a cross-sectional view of various embodiments of a method of stacking wafers with anisotropic conductive adhesive according to the present invention.

*1A -1K are*

[0006]       **Figure 1-K** is also an illustration of a cross-sectional view of various embodiments of a stacked-wafer structure having anisotropic conductive adhesive according to the present invention.